

Attorney Docket No.: 111079-135918  
IPN P14927X (Intel Corporation)

OCT 07 2005 Patent

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application of:

**Boggs, et al.**

Application No.: 10/750,560

Filed: December 31, 2003

For: **Electronic Substrate with Direct  
Inner Layer Component  
Interconnection**

Examiner: Ishwarbhai B. Patel

Art Unit: 2841

Confirmation No. 5692

**CERTIFICATE OF TRANSMISSION/MAILING**

I hereby certify that this correspondence is being facsimile transmitted to the USPTO or deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, PO Box 1450, Alexandria, VA 22313-1450 on the date shown below:

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Date: 10/07/2005

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**AMENDMENT AND RESPONSE TO FINAL OFFICE ACTION**

Dear Sir:

This communication is submitted in response to the Final Office Action mailed August 8, 2005. Applicants respectfully request reconsideration of the captioned application in view of the amendments and remarks to follow.

**Amendments to the Specification** – none;

**Amendments to the Claims** – are reflected in the listing of claims that begin on page 2 of this paper;

**Amendments to the Drawings** – none; and

**Remarks/Arguments** – begin on page 6 of this paper.

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